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# 2SA2186

## Bipolar Transistor -50V, -2A, Low VCE(sat), PNP Single NMP

ON Semiconductor®

<http://onsemi.com>

### Applications

- Voltage regulators, relay drivers, lamp drivers, electrical equipment

### Features

- Adoption of MBIT processes
- Low collector-to-emitter saturation voltage
- Large current capacity
- High-speed switching

### Specifications

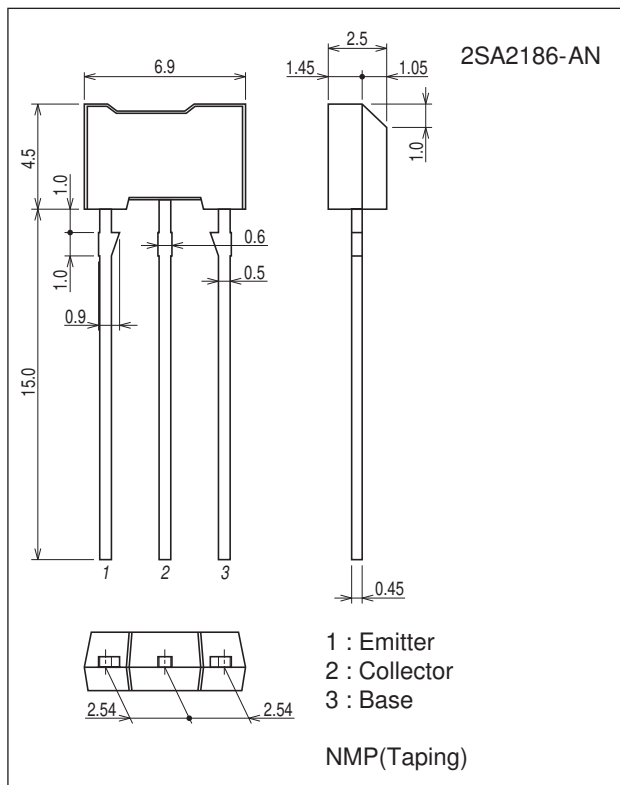
**Absolute Maximum Ratings** at Ta=25°C

Parameter	Symbol	Conditions	Ratings	Unit
Collector-to-Base Voltage	V <sub>CBO</sub>		-50	V
Collector-to-Emitter Voltage	V <sub>CEO</sub>		-50	V
Emitter-to-Base Voltage	V <sub>EBO</sub>		-6	V
Collector Current	I <sub>C</sub>		-2	A
Collector Current (Pulse)	I <sub>CP</sub>		-4	A
Base Current	I <sub>B</sub>		-400	mA
Collector Dissipation	P <sub>C</sub>		0.9	W
Junction Temperature	T <sub>j</sub>		150	°C
Storage Temperature	T <sub>stg</sub>		-55 to +150	°C

Stresses exceeding Maximum Ratings may damage the device. Maximum Ratings are stress ratings only. Functional operation above the Recommended Operating Conditions is not implied. Extended exposure to stresses above the Recommended Operating Conditions may affect device reliability.

### Package Dimensions

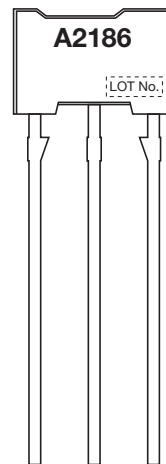
unit : mm (typ)  
7540-001



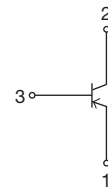
### Product & Package Information

- Package : NMP(Taping)
- JEITA, JEDEC : SC-71
- Minimum Packing Quantity : 2,500 pcs./box

### Marking(NMP(Taping))



### Electrical Connection

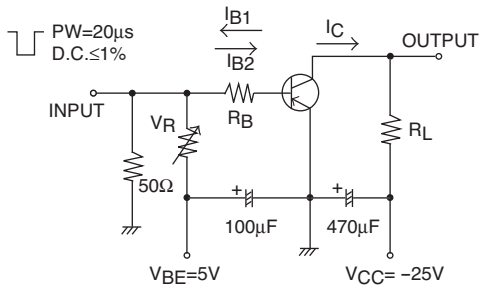


## 2SA2186

### Electrical Characteristics at Ta=25°C

Parameter	Symbol	Conditions	Ratings			Unit
			min	typ	max	
Collector Cutoff Current	$I_{CBO}$	$V_{CB}=-40V, I_E=0A$			-1	$\mu A$
Emitter Cutoff Current	$I_{EBO}$	$V_{EB}=-4V, I_C=0A$			-1	$\mu A$
DC Current Gain	$h_{FE1}$	$V_{CE}=-2V, I_C=-100mA$	200		560	
	$h_{FE2}$	$V_{CE}=-2V, I_C=-1.5A$	40			
Gain-Bandwidth Product	$f_T$	$V_{CE}=-10V, I_C=-300mA$		420		MHz
Output Capacitance	$C_{ob}$	$V_{CB}=-10V, f=1MHz$		16		pF
Collector-to-Emitter Saturation Voltage	$V_{CE(sat)}$	$I_C=-1A, I_B=-50mA$		-0.22	-0.43	V
Base-to-Emitter Saturation Voltage	$V_{BE(sat)}$	$I_C=-1A, I_B=-50mA$		-0.9	-1.2	V
Collector-to-Base Breakdown Voltage	$V_{(BR)CBO}$	$I_C=-10\mu A, I_E=0A$	-50			V
Collector-to-Emitter Breakdown Voltage	$V_{(BR)CEO}$	$I_C=-1mA, R_{BE}=\infty$	-50			V
Emitter-to-Base Breakdown Voltage	$V_{(BR)EBO}$	$I_E=-10\mu A, I_C=0A$	-6			V
Turn-ON Time	$t_{on}$	See specified Test Circuit.		35		ns
Storage Time	$t_{stg}$			200		ns
Fall Time	$t_f$			24		ns

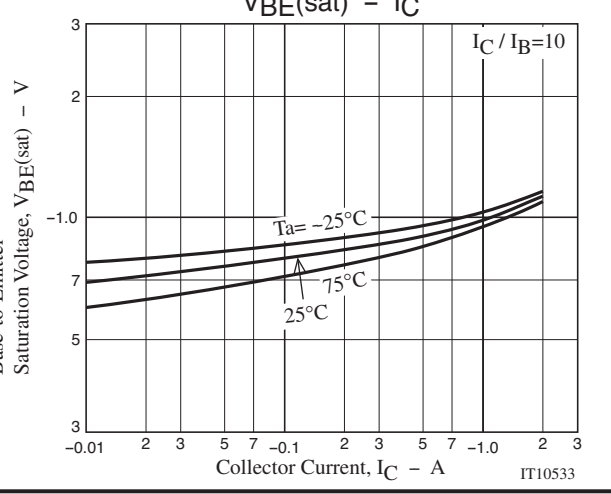
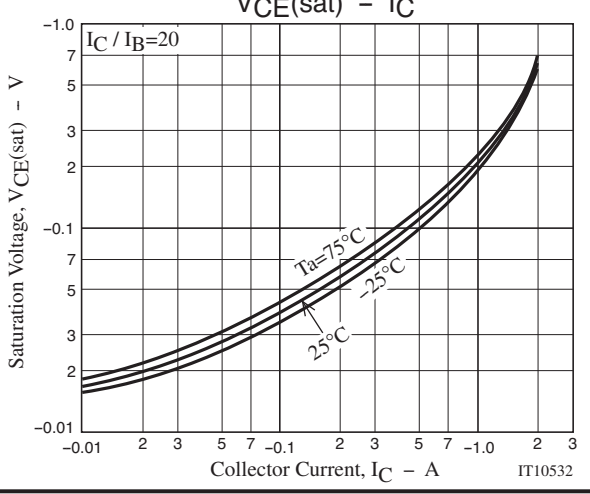
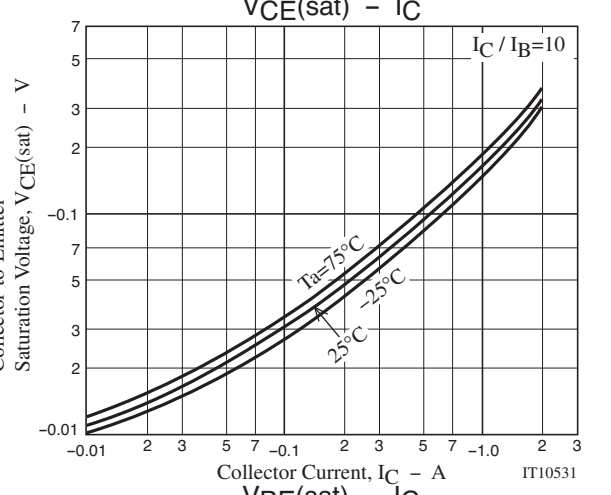
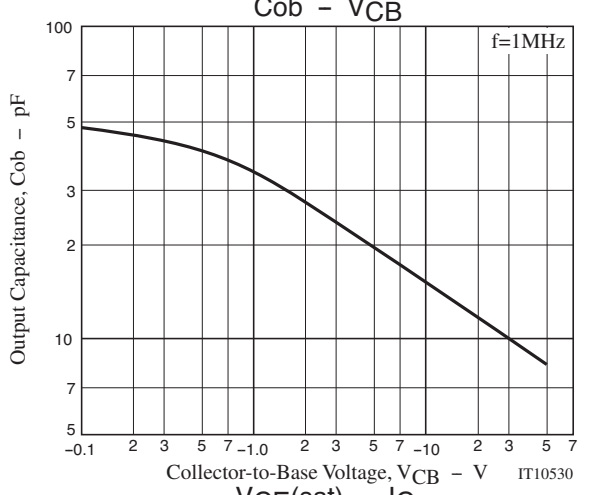
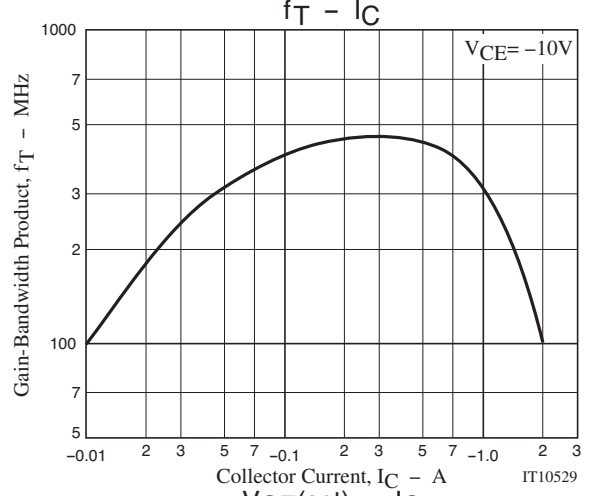
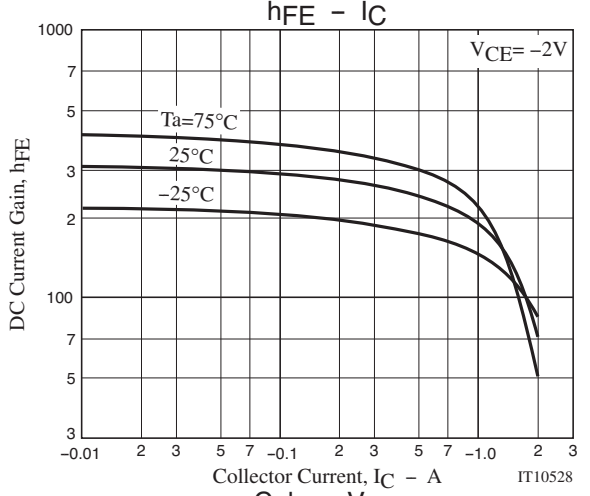
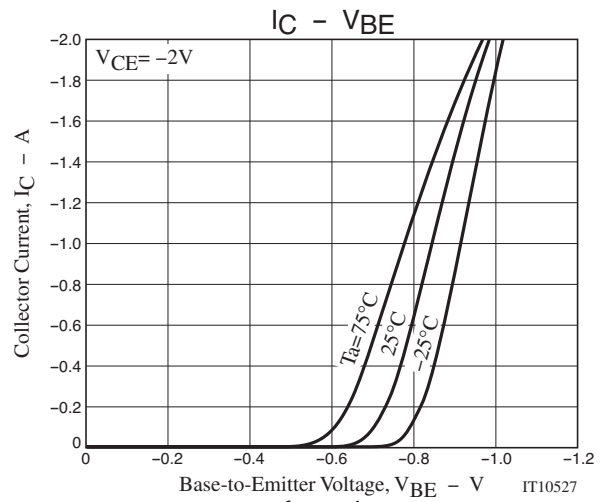
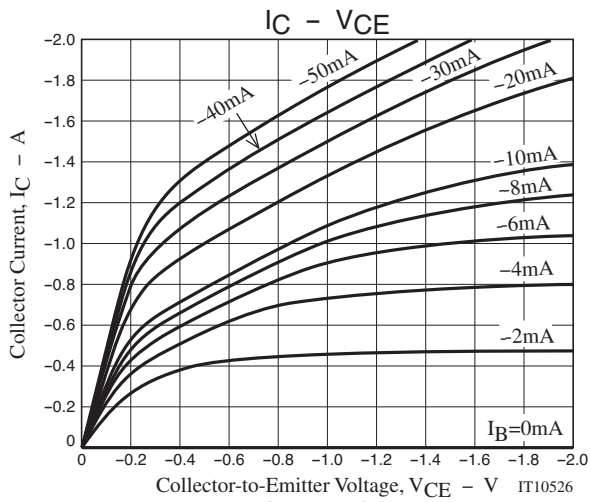
### Switching Time Test Circuit

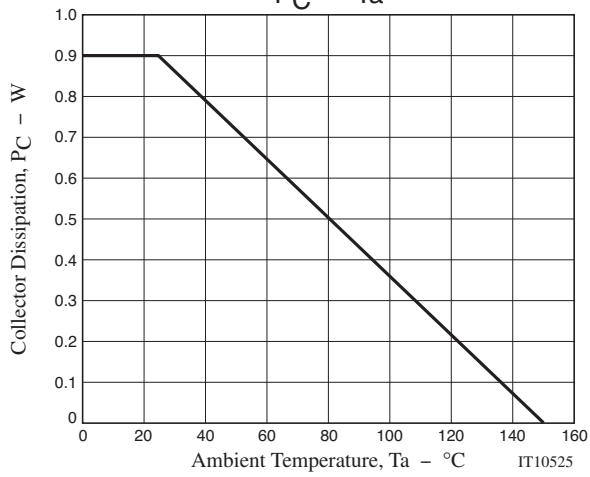
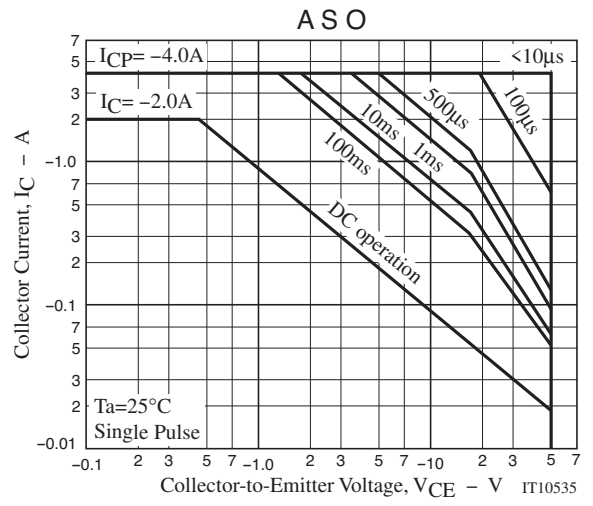
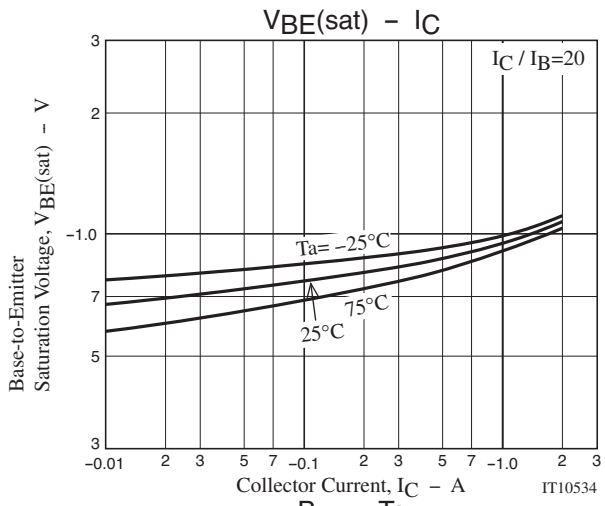


$$I_C = 10I_{B1} = -10I_{B2} = -0.7A$$

### Ordering Information

Device	Package	Shipping	memo
2SA2186-AN	NMP(Taping)	2,500pcs./box	Pb Free





Bag Packing Specification

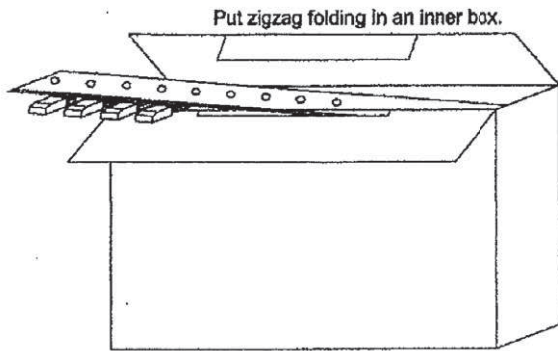
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NMP (Zigzag folding)

Storage package Outline name	Package type	Maximum Number of devices contained (pcs.)		Packing format	
		Inner box No.	Storage quantity	Outer box (C-6)	Outer box (C-8)
NMP	AN/AZ	C-3 Inner box Dimensions :mm(external) 330×45×125	2,500	8 inner boxes contained(20,000pcs.) Outer box Dimensions:mm(external) 585×345×195	4 inner boxes contained(10,000pcs.) Outer box Dimensions:mm(external) 345×300×195

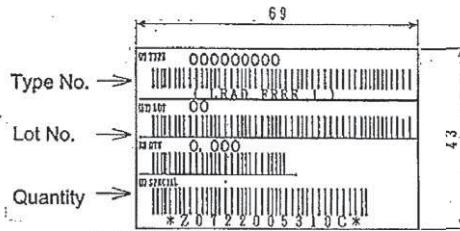
1. Packing format

Packing method



2. Bar code label

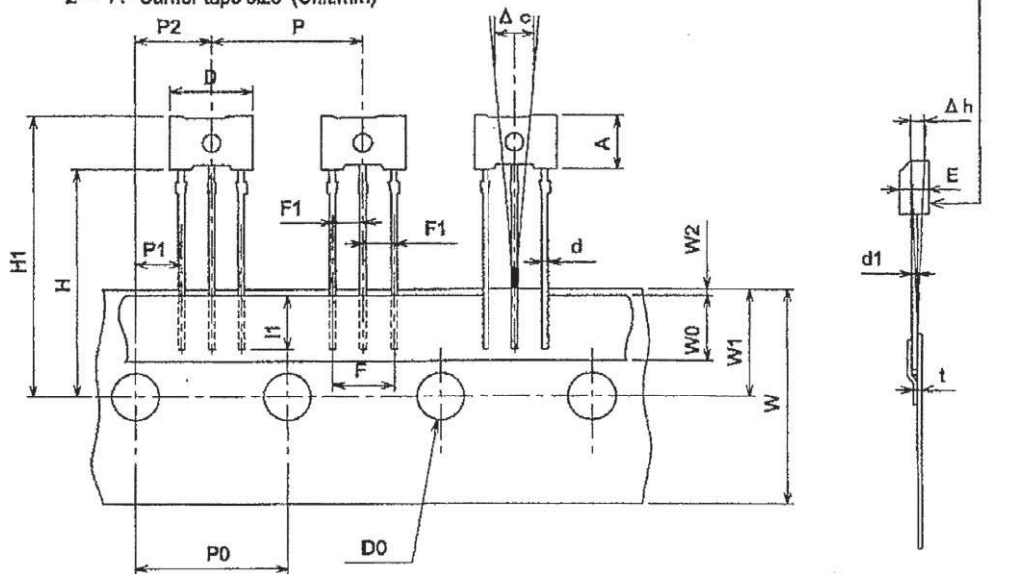
(Unit : mm)



\*LEAD FREE 1 :  
Lead-free External terminal surface treatment product.

2. Taping specifications

2-1. Carrier tape size (Unit:mm)



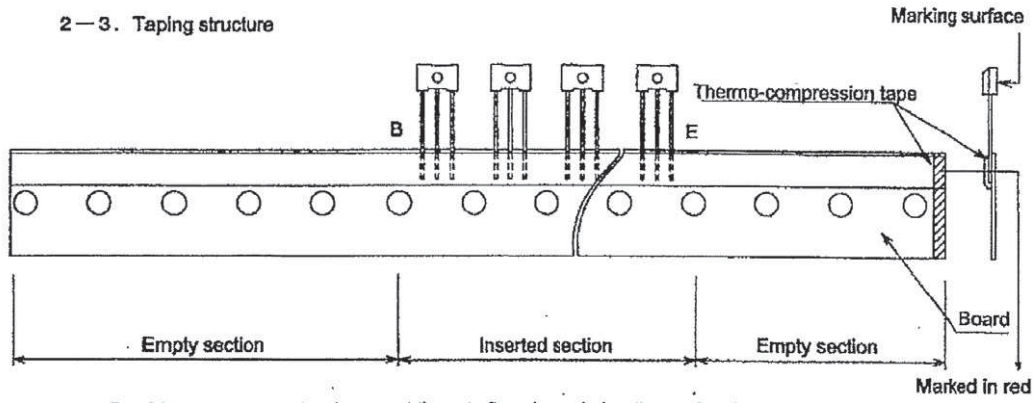
2-2. Taping size standard

Item	Symbol	Standard	Tolerance
Work piece outside diameter	D	6.9	±0.2
	E	2.5	±0.2
Work piece height	A	4.5	±0.2
Lead wire diameter	d	0.5	±0.1
Lead wire thickness	d1	0.45	±0.1
Bonded lead wire	l1	3.0MIN	
Pitch between products	P	12.7	±0.5
Pitch between perforations	P0	12.7	±0.2
Total pitch for 21 perforations	P0×20	254.0	±1.0
Distance between lead wire	F	5.0	+0.8 -0.2
Lead wire pitch distance	F1	2.54	+0.4 -0.1
Displacement of perforations	P1	3.81	±0.3
	P2	6.35	±0.3
Displacement of tape	W2	0~0.5	

Unit:mm

Item	Symbol	Standard	Tolerance
Tape width	W	18.0	±0.5
Adhesive tape	W0	6.0	±0.5
Displacement of perforations	W1	9.0	±0.5
Work piece bottom surface position	H	19.0	+1.0 -0.5
Work piece upper limit position	H1	23.5	±1.0
Perforations diameter	D0	φ4.0	±0.2
Tape thickness (total thickness)	t	0.6	±0.2
Product inclination	Δc	0	±0.7
Product inclination	Δh	0	±1.0

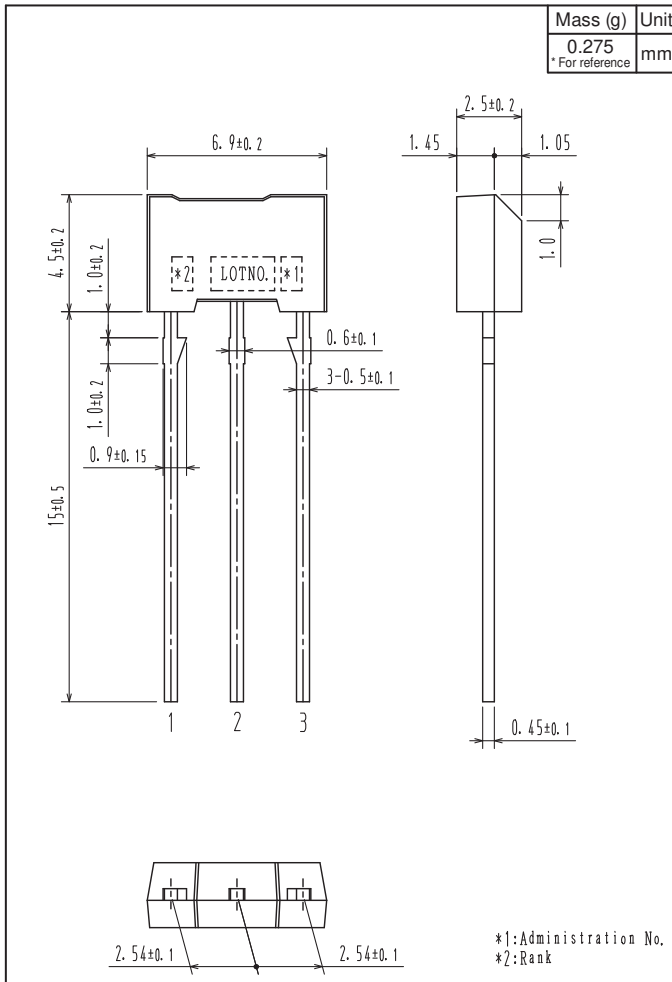
2—3. Taping structure



- Provide an empty section for about three to five pieces in leading and end portions of the tape.
- Provide an empty section in the fold-back portion.
- Provide marking in red to the E-side end of the board.

Outline Drawing

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